Amendments to the Claims: This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Currently amended) A heat sink configured to support an edge of a circuit card, said heat sink comprising:

a thermally conductive base;

a plurality of thermally conductive heat dissipating fins extending from said base; and

one or more recesses at least partially defined by at least one of said fins~~,~~ the recesses having a depth smaller than the height of said fins, said one or more recesses being configured to support the edge of the circuit card.

2. (Original) The heat sink of claim 1 wherein said base and said fins are formed by extrusion.

3. (Original) The heat sink of claim 1 wherein said one or more recesses are further configured to support the edge of the circuit card in sliding association with said heat sink.

4. (Original) The heat sink of claim 3 wherein said recess is a slot configured to guide the edge of the circuit card during sliding movement of the circuit card.

5. (Original) The heat sink of claim 1 further comprising a face disposed opposite said fins, said base being configured to be mounted with said face abutting a heat-generating component.

6. (Original) The heat sink of claim 1 wherein said recess is defined by said base.

7. (Previously Presented) The heat sink of claim 1 wherein said recess is defined by a plurality of said fins.

8. (Canceled)

9. (Original) The heat sink of claim 1 wherein said fins are oriented substantially parallel to one another.

10. (Currently amended) A method for supporting a circuit card in a computer system, said method comprising performing in order the steps of:

affixing in a computer system a heat sink having a recess configured to receive an edge of a circuit card, thereby orienting the heat sink to position the recess to receive an edge of the circuit card, the recess at least partially defined by at least one of a plurality of thermally conductive heat dissipating fins, the recess having a depth smaller than the height of said fins; and

positioning the edge of the circuit card in the recess.

11. (Original) The method of claim 10, wherein said positioning step comprises sliding the circuit card in the recess.

12. (Original) The method of claim 10, wherein said affixing step comprises affixing the heat sink to a heat-generating component.

13. (Original) The method of claim 12 wherein the heat-generating component is mounted on a circuit board, and said affixing step comprises affixing the heat sink with the recess disposed opposite the heat-generating component.

14. (Original) The method of claim 10, wherein the circuit card carries at least one heat generating component, and said positioning step comprises thermally coupling the heat-generating component to the heat sink when the circuit card is positioned in the recess.

15. (Currently amended) A circuit board assembly comprising:

a circuit board;

a heat generating component mounted on said circuit board; and

a heat sink thermally coupled to said heat generating component and having a plurality of fins for dissipating heat, said heat sink defining a recess for supporting and guiding an edge of a circuit card,

said recess at least partially defined by at least one of said fins and having a depth smaller than the height of said fins.

16. (Original) The circuit board assembly of claim 15 wherein said circuit card comprises an edge portion in sliding association with said recess.

17. (Original) The circuit board assembly of claim 15 further comprising a connector configured for electrically coupling said circuit card to a computer system, said recess of said heat sink being oriented to guide said circuit card for coupling said connector to said computer system.

18. (Currently amended) A heat sink guiding one or more circuit cards and transferring heat from one or more heat-generating components, said heat sink comprising:

a surface defining one or more slots configured to guide an edge of a circuit card; and

heat dissipating fins thermally coupled to said surface,

said one or more slots at least partially defined by at least one of said fins said one or more slots having a depth smaller than the height of said fins;

said heat sink being configured to provide a thermal path from a heat-generating component to said fins via said surface.

19. (Original) The heat sink of claim 18 further comprising a surface disposed opposite said slots and configured to be mounted in thermal contact with said one or more heat-generating components.

20. (Original) The heat sink of claim 18 having a substantially constant cross-sectional shape.

21. (Currently amended) A method for guiding a circuit board in a computer system, said method comprising:

sliding an edge portion of the circuit board in a recess defined by a heat sink of the computer system, and having a depth smaller than the height of fins of the heat sink,

thereby guiding the circuit board.